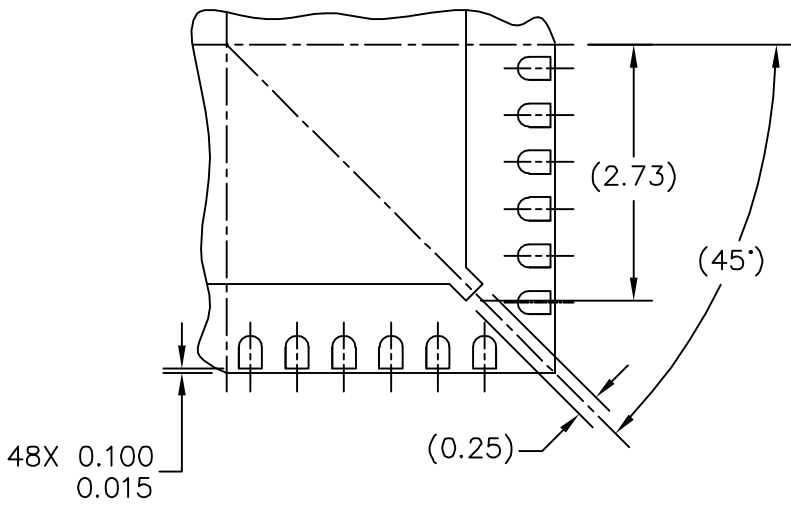
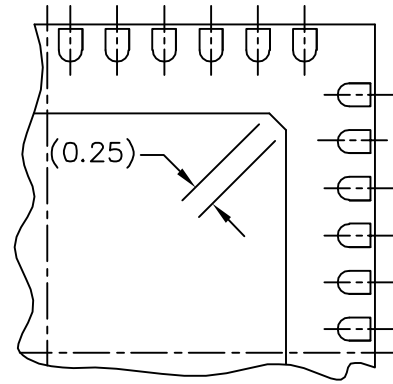


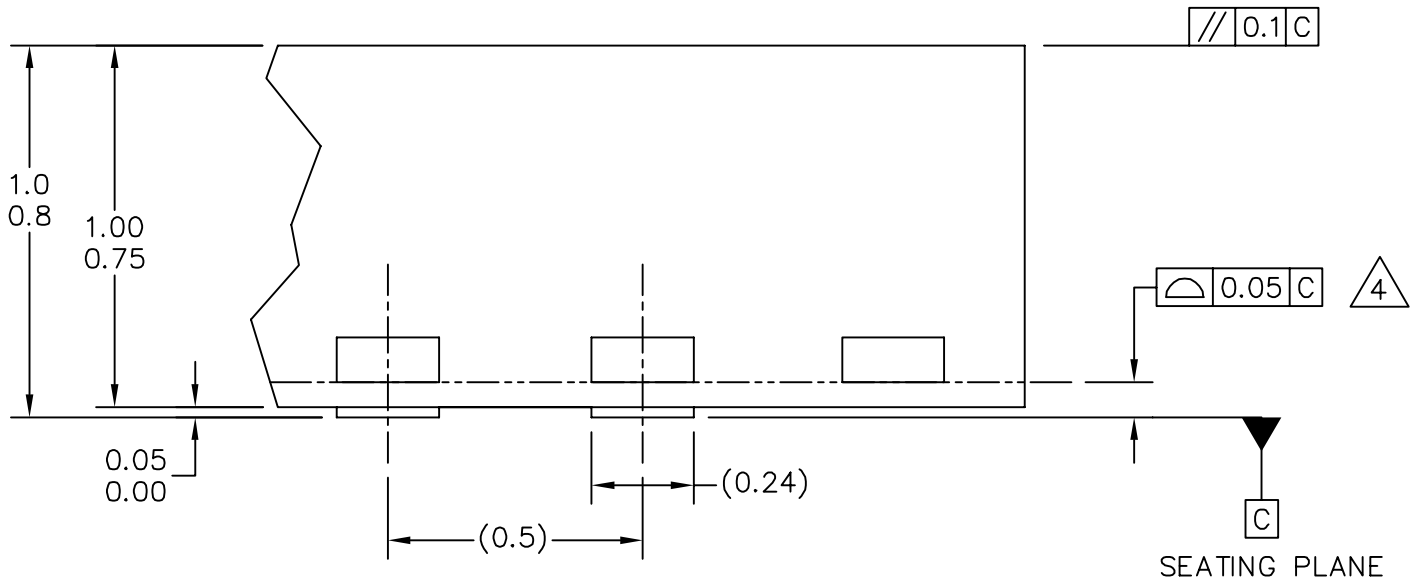
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 48 TERMINAL, 0.5 PITCH (7 X 7 X 1)	DOCUMENT NO: 98ARH99048A	REV: F	
	CASE NUMBER: 1314-05	05 DEC 2005	
	STANDARD: JEDEC-MO-220 VKKD-2		



DETAIL N
PREFERRED CORNER CONFIGURATION

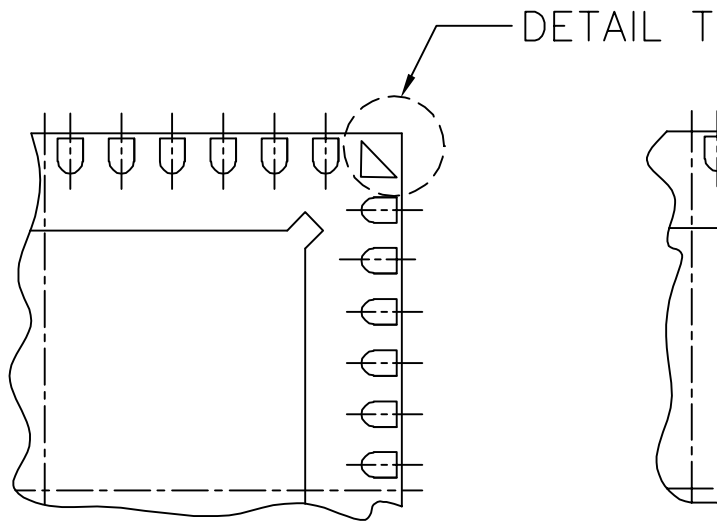


DETAIL M
PREFERRED PIN 1 BACKSIDE IDENTIFIER



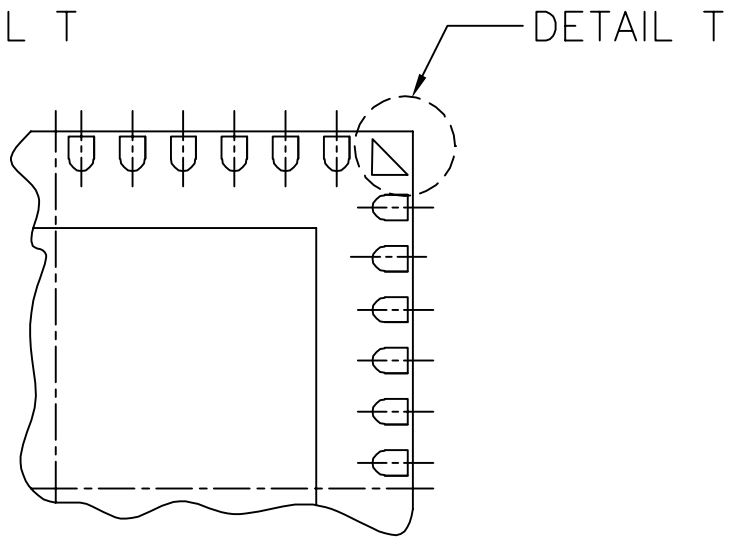
DETAIL G
VIEW ROTATED 90° CW

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 48 TERMINAL, 0.5 PITCH (7 X 7 X 1)	DOCUMENT NO: 98ARH99048A	REV: F	
	CASE NUMBER: 1314-05	05 DEC 2005	
	STANDARD: JEDEC-MO-220 VKKD-2		



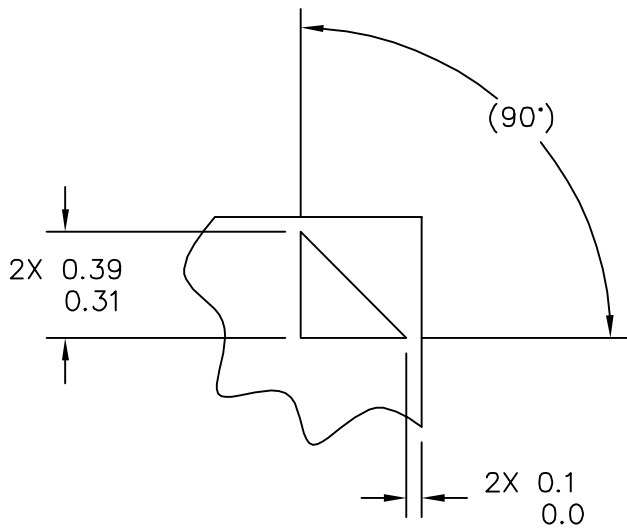
DETAIL M

PIN 1 BACKSIDE IDENTIFIER OPTION



DETAIL M


PIN 1 BACKSIDE IDENTIFIER OPTION



DETAIL T

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	CASE NUMBER: 1314-05	05 DEC 2005	
	STANDARD: JEDEC-MO-220 VKKD-2		

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2MM.

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